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(54) **EMBEDDED PACKAGE STRUCTURE, POWER SUPPLY APPARATUS, AND ELECTRONIC DEVICE**

(57) This application provides an embedded package structure, a power supply apparatus, and an electronic device. First electronic components with smaller sizes are stacked, and then arranged in a substrate frame in a two-dimensional manner with a larger-size inductor component to form an embedded package structure. This can reduce an area occupied by the entire embedded package structure, and reduce an overall size of the structure, thereby facilitating integration and miniaturization. Then, a chip is disposed on the embedded package

structure, so that the chip serving as a main heat source is placed on a surface of the power supply apparatus. Compared with an existing power module structure in which a chip is embedded in a substrate to form an ECP module and an inductor is mounted on a surface of the ECP module, in the embedded package structure provided in this application, a main heat dissipation path of the chip is changed from an existing downward heat dissipation direction to an upward heat dissipation direction, which may improve a heat dissipation capability.

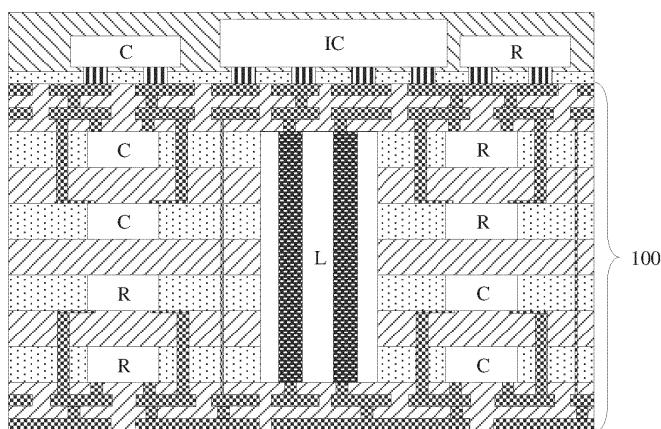


FIG. 8



EUROPEAN SEARCH REPORT

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50	2 The present search report has been drawn up for all claims		
55	Place of search The Hague	Date of completion of the search 12 March 2024	Examiner Kästner, Martin
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